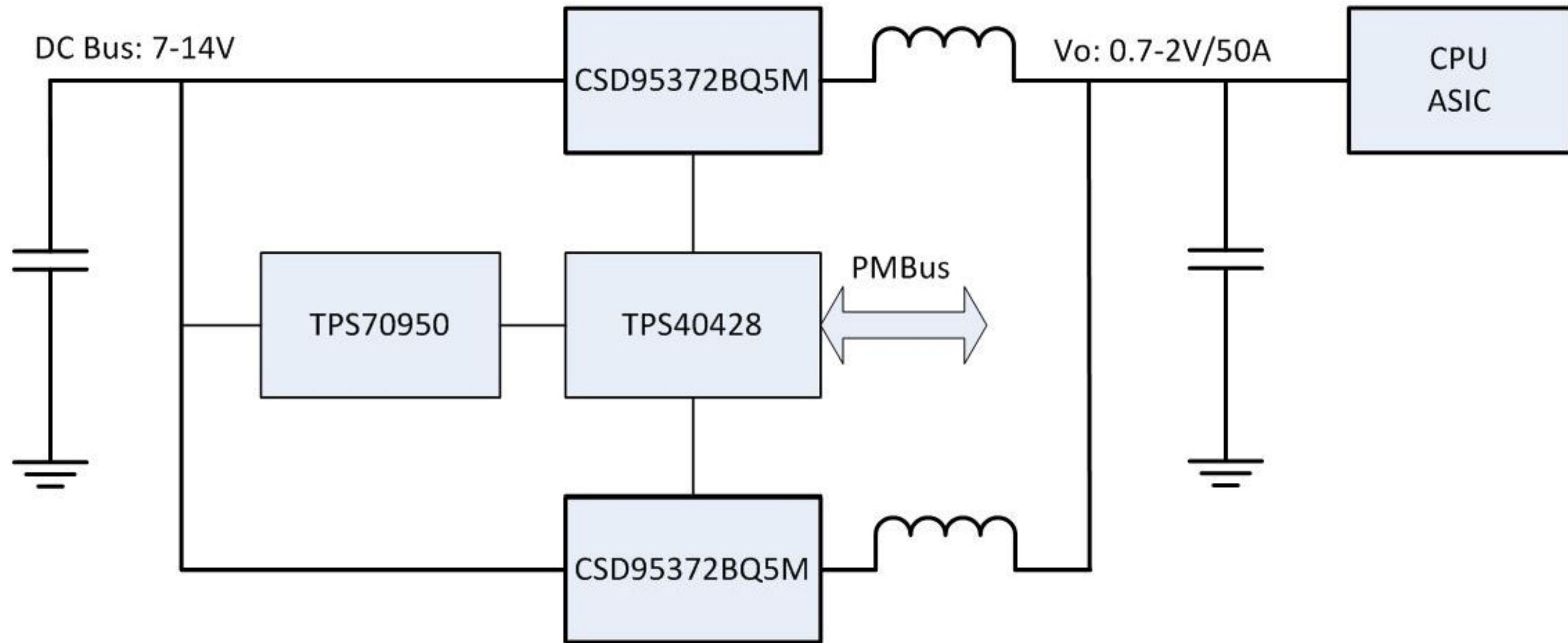
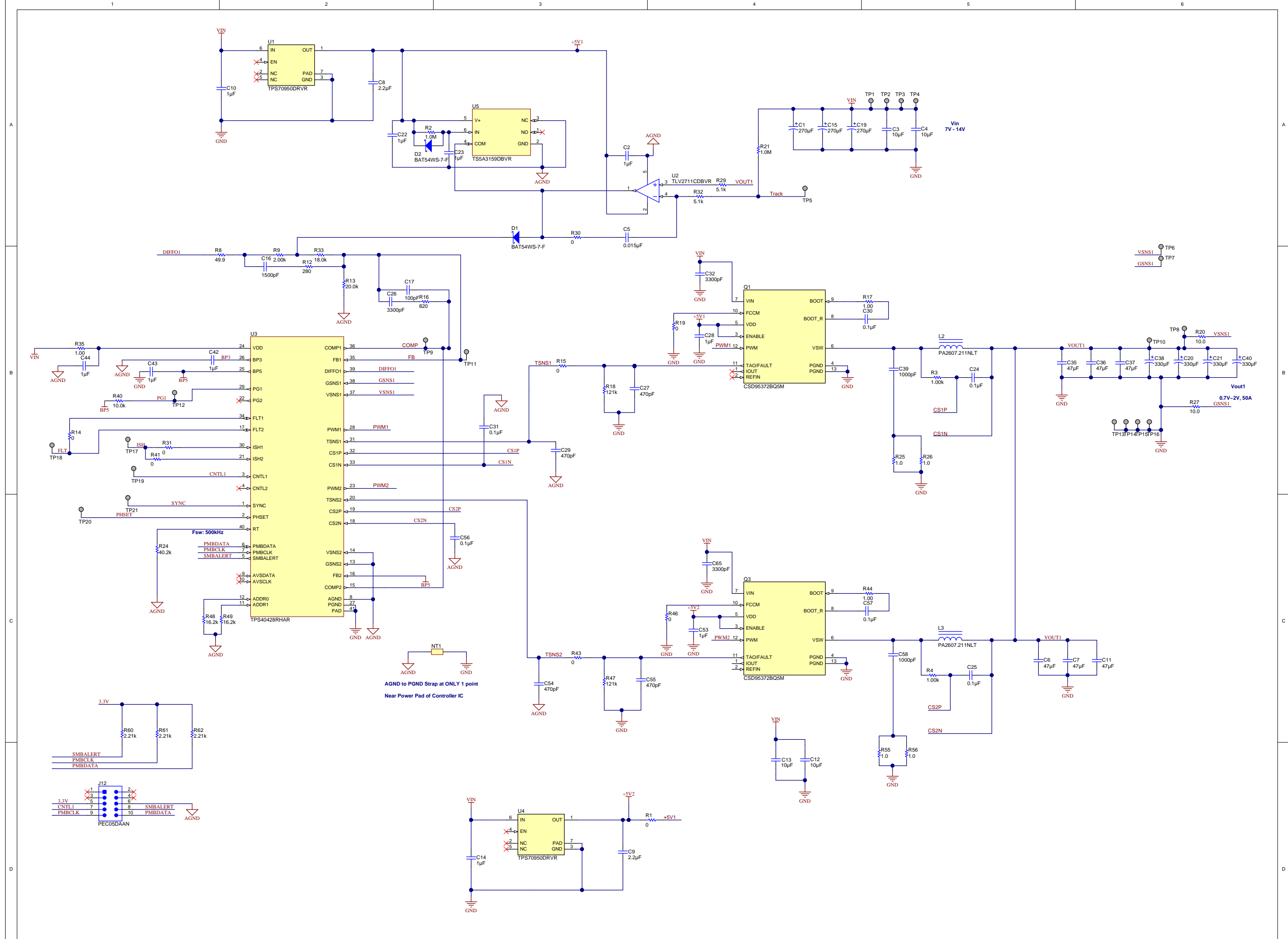


Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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Orderable: N/A	Designed for: Public Release	Mod. Date: 10/28/2016	 http://www.ti.com
TID #: PMP4482	Project Title: 12Vin Dual-phase 50A Intelligent Power Module On	Sheet: 1 of 2	
Number: PMP4482	Rev: A	File: PMP4482_CoverSheet.SchDoc	Size: B
SVN Rev: Version control disabled	Assembly Variant: 001	Contact: http://www.ti.com/support	© Texas Instruments 2016
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AGND to PGND Strap at ONLY 1 point  
Near Power Pad of Controller IC

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